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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Ralf Otremba	04/11/2007
Xaver Schloegel	05/30/2007
Khai Huat Jeffrey Low	05/14/2007
Chee Soon Law	05/14/2007

RECEIVING PARTY DATA

Name:	Infineon Technologies AG	
Street Address:	StMartin-Strasse 53	
City:	Muenchen	
State/Country:	GERMANY	
Postal Code:	81669	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	11725973

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER:	2006 P 54606 (LL)
NAME OF SUBMITTER:	Julie Russell

PATENT REEL: 019429 FRAME: 0184

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Total Attachments: 2 source=2006 P 54606 Assignment#page1.tif source=2006 P 54606 Assignment#page2.tif

> PATENT REEL: 019429 FRAME: 0185

Attorney Docket No. 2006 P 54606 US

ASSIGNMENT

For good and valuable consideration, I, Ralf Otremba, residing at Ahornstrasse 42, 87600

Kaufbeuren, Germany, a citizen of Germany; Xaver Schloegel, residing at Raiffeisenstrasse 22,

83679 Sachsenkam, Germany, a citizen of Germany; Khai Huat Jeffrey Low, residing at 99 Jalan

Sentosa 11, 75150 Melaka, Malaysia, a citizen of Malaysia; Chee Soon Law, residing at No. 8

Jalan Setia Jaya 1, Taman Setia Jaya, Bukit Piatu, 75150 Melaka, Malaysia, a citizen of Malaysia;

hereby sell, assign, and transfer to Infineon Technologies AG, a corporation organized and

existing under the laws of Germany, having its principal place of business at St.-Martin-Strasse 53,

Muenchen, 81669, Germany;

hereinafter "Assignee", its successors, assigns and legal representatives, the entire right, title

and interest in and for the United States and all foreign countries, in and to any and all

improvements which are disclosed in the application for United States Letters Patent, which has

been executed by the undersigned concurrently herewithin, and is entitled:

Module Comprising a Semiconductor Chip

and in and to said application and all divisional, continuing substitute, renewal, reissue, and all

other applications for Letters Patent which have been or shall be filed in the United States and all

foreign countries on any of said improvements; and in and to all original and reissued patents which

have been or shall be filed in the United States and all foreign countries on said improvements;

Agree that Assignee may apply for and receive Letters Patent for said improvements in its

own name, and that, when requested, without charge to but at the expense of said Assignee, their

successors, assigns, and legal representatives to carry out in good faith the intent and purpose of this

agreement, the undersigned will execute all divisional, continuing substitute, renewal, reissue, and

all other patent applications on any and all said improvements; execute all rightful oaths,

assignments, powers of attorney and other papers; communicate to said Assignee, its successors,

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PATENT

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assigns, and representatives, all facts known to the undersigned relating to said improvements and the history thereof; and generally do everything possible which said Assignee, its successors, assigns, or representatives shall consider desirable for aiding in securing and maintaining proper patent protection for said improvements and for vesting title to said improvements and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns, and legal representatives; and

Covenant with said Assignee, its successors, assigns and legal representatives that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

Date: N.04. 2007

Date: 30.05.200Z

Date: 14 -05 -2007

Date: 14.05.207.

Ralf Otremba

Vi Cuto I

Khai Huat Jeffrey Low

Chee Soon Law